

S29NS256R

CS Q06566

Qualification of: S29NS256R, 256 Megabit (16 M x 16 bit), 1.8 V Burst, Simultaneous Read/Write Multiplexed MirrorBit Flash Memory in VDJ044 (7.7 x 6.2 x 1.0mm) 44 Ball, Very Thin Fine Pitch Ball Grid Array Package (FBGA)



Reliability Qualification Summary

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NOTICE: The material in this report is confidential. It is prepared to assist in the qualification of our product. It is declassified for the internal use of our customers only, and may be modified to meet the needs of specific customers. It also serves as a record of full qualification according to JESD47 and AEC-Q100 Grade 1 requirements.

Additionally, the package details (material set, assembly location, etc.) are specific to the qual vehicle used for the qualification. Alternate material sets and assembly locations may be qualified for the product. Production material can be assembled with any qualified material set and at any qualified assembly location. Tests are performed in accordance with AEC-Q100 and relevant JEDEC specifications.

Table of Contents

- I. Product Information
- II. Life Test Failure Rate Calculation
- III. Summary of Stress Test Results
- IV. Revision History

I. Product Information

Product Description: S29NS256R
256 Megabit (16 M x 16 bit), 1.8 V Burst, Simultaneous Read/Write
Multiplexed MirrorBit® Flash Memory

Package:	VDJ044	Qualification:	Q06566
Description:	(7.7 x 6.2 x 1.0mm) 44 Ball, Very Thin Fine Pitch Ball Grid Array Package (FBGA)		
Theta Ja:	39 °C/W	Psi Jt:	11 °C/W
Assembly Location:	Spansion Thailand	Molding Compound:	RoHS Compliant Epoxy Resin
Substrate/Leadframe:	BT Resin Substrate	Die Attachment:	Paste
Lead Finish:	98.3Sn1.2Ag0.5Cu Spheres	Bond Wire:	Gold
Comments:			

Est. Field Temperature:	55 °C	Life Test Temperature:	150 °C
Est. DC Field Current:	52 mA	Life Test Dynamic Current:	20 mA
Est. Field Voltage:	1.8 V	Life Test Voltage:	1.95 V
Est. Field Power Dissipation:	93.6 mWatts	Est. Stress Power Dissipation:	39 mWatts
Est. Field Tj:	58.6 °C	Est. Stress Tj:	151.5 °C

Die:	98253B	Die Size:	5.10 x 5.65 mm
Process:	CS239L (65nm)	Fab:	Spansion SP1
Type:	MirrorBit	Density:	256M

II. CS239/L Life Test Failure Rate Calculation

HTOL Stress Temperature - 125 °C

Failure Mechanism	Read Points / Test Results				Modeling Parameters @ 55°C					Avg. Failure Rate FITS @ 55°C, 60% Conf.	
	24 hrs	168 hrs	1000 hrs	2000 hrs	Ea eV	TAF	VAF	OAF	MTTF (yrs)	Early Life	Inherent Life
PLASTIC											
Sample Size	3882	3880	540	100							
Zero fails, Process ave. Ea	0 *	0	0	0	0.66	41	1	41		59	19
Totals	0	0	0	0					6008	59	19

* Contributes to early life FITS

Data Retention Bake - 150 °C

Reliability Stress	Number of Rejects	Sample Size	Failure Rate %	Failure Mechanism
500 hrs	0	1200	0.00	No Failures
1000 hrs	0	1098	0.00	No Failures

III. Summary of Stress Test Results

Stress Test	Stress Condition	Package Type	Sample Size	Num. of Lots	Num. of Fails	Failure Rate %	Comments
Data From Qualification Q06566:							
HTOL (EL)	(1.95V, 150°C)	VDJ044 ¹	76	1	0	0.00	168 hours
Data Retention Bake	(150°C)	VDJ044 ¹	73	1	0	0.00	84 hours
	(150°C)	VDJ044 ¹	73	1	0	0.00	48 hours
ESD CDM	N/A	VDJ044 ¹	15	1	Passed 1.0kV		
ESD HBM	(100pF, 1500 Ohms)	VDJ044 ¹	81	1	Passed 2.0kV		
Latch Up	(125°C, +/- 100mA)	VDJ044 ¹	6	1	Passed		
Endurance (10k)	(-25°C, 1.7V)	VDJ044 ¹	57	1	0	0.00	10k cycles
	(-25°C, 1.95V)	VDJ044 ¹	63	1	0	0.00	10k cycles
	(90°C, 1.7V)	VDJ044 ¹	64	1	0	0.00	10k cycles
	(90°C, 1.95V)	VDJ044 ¹	61	1	0	0.00	10k cycles
Generic Reference Data:							
Preconditioning	(PC1/260°C, +0°C/-5°C)	VDH064 ²	231	2	Passed Jedec L3 / Jeita Rank E		
Precon+Temp Cycle	(PC1/260°C, -40°C/150°C)	VDH064 ²	77	1	0	0.00	500 cycles
Precon+HAST	(PC1/260°C, Biased, 110°C/85% RH)	VDH064 ²	77	2	0	0.00	96 hours
Precon+uHAST	(PC1/260°C, Unbiased, 130°C/85% RH)	VDH064 ²	77	2	0	0.00	96 hours

Notes / Justification: 1) Results from Qual Q06566, S29NS256R, 256M CS239L (65nm) MirrorBit in 44 Ball vFBGA (7.7 x 6.2 x 1mm)
 2) Results from Qual Q99023, S29NS512R in 64 Ball vFBGA (8 x 9.2 x 1mm) - Same Flash Technology, Similar Package as S29NS256R (Note #1)

Preconditioning Flows: PC1 (Exceeds JEDEC L3 and JEITA Rank E): Bake 125°C, 24hr => Soak @ 30°C/70%RH, 216hr => 3x Reflow

IV. Revision History

Section	Description
Revision A - 4/3/2008	Initial Release.

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